Product Change Notification - KSRA-27FAPU261

Date: 31 Aug 2017

Product Category: Capacitive Touch Sensors; Touch Controllers; 8-bit PIC Microcontrollers

Notification subject: CCB 3042 and CCB 3074 Initial Notice: Qualification of CuPdAu bond in selected products of the 200K wafer technology available in 8L DFN package at NSEB assembly site

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach material, G770HCD or G700LTD molding compound material and EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire 8600 die attach material, G700LTD molding compound material and C194 lead frame material

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	NSEB Assembly Site		NSEB Assembly Site
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:

January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been

issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2017					-->	January 2018				
Workweek	31	32	33	34	35		01	02	03	04	05
Initial PCN Issue Date	X										
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:
August 02, 2017: Issued initial notification.
August 31, 2017: Re-issued initial notification to include CCB 3074.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-27FAPU261_Affected CPN.pdf
PCN_KSRA-27FAPU261_Qual Plan.pdf
PCN_KSRA-27FAPU261_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

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To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Numbers (CPN)

PCN_ KSRA-27FAPU261
CATALOG_PART_NBR
MTCH112-I/MF
MTCH112T-I/MF
MTCH810-I/MF
MTCH810T-I/MF
PIC10F320-E/MC
PIC10F320-I/MC
PIC10F320T-E/MC
PIC10F320T-I/MC
PIC10F322-E/MC
PIC10F322-I/MC
PIC10F322T-I/MC
PIC10LF320-E/MC
PIC10LF320-I/MC
PIC10LF320T-I/MC
PIC10LF322-E/MC
PIC10LF322-I/MC
PIC10LF322T-I/MC
PIC12F1501-E/MC
PIC12F1501-E/MF
PIC12F1501-I/MC
PIC12F1501-I/MC029
PIC12F1501-I/MF
PIC12F1501T-E/MC
PIC12F1501T-E/MF
PIC12F1501T-I/MC
PIC12F1501T-I/MC023
PIC12F1501T-I/MC025
PIC12F1501T-I/MC030
PIC12F1501T-I/MF
PIC12F1571-E/MF
PIC12F1571-I/MF
PIC12F1571T-I/MF
PIC12F1572-E/MF
PIC12F1572-I/MF
PIC12F1572T-I/MF
PIC12F1612-E/MF
PIC12F1612-I/MF
PIC12F1612T-I/MF
PIC12F1822-E/MF
PIC12F1822-I/MF
PIC12F1822-I/MF043
PIC12F1822T-E/MF
PIC12F1822T-I/MF

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Affected Catalog Part Numbers (CPN)

PCN_ KSRA-27FAPU261
CATALOG_PART_NBR
PIC12F1840-E/MF
PIC12F1840-H/MF
PIC12F1840-I/MF
PIC12F1840T-E/MF
PIC12F1840T-H/MF
PIC12F1840T-I/MF
PIC12LF1501-E/MC
PIC12LF1501-E/MF
PIC12LF1501-I/MC
PIC12LF1501-I/MC020
PIC12LF1501-I/MF
PIC12LF1501T-E/MC
PIC12LF1501T-I/MC
PIC12LF1501T-I/MC020
PIC12LF1501T-I/MC021
PIC12LF1501T-I/MF
PIC12LF1571-E/MF
PIC12LF1571-I/MF
PIC12LF1571T-I/MF
PIC12LF1572-E/MF
PIC12LF1572-I/MF
PIC12LF1572T-I/MF
PIC12LF1612-E/MF
PIC12LF1612-I/MF
PIC12LF1612T-I/MF
PIC12LF1822-E/MF
PIC12LF1822-I/MF
PIC12LF1822-I/MF023
PIC12LF1822-I/MFC02
PIC12LF1822T-I/MF
PIC12LF1822T-I/MF023
PIC12LF1840-E/MF
PIC12LF1840-I/MF
PIC12LF1840T-I/MF